



# SGM4895

## 1.3W Fully Differential Audio Power Amplifier

### GENERAL DESCRIPTION

The SGM4895 is a fully differential audio power amplifier that is designed for portable communication device applications and demanding applications in mobile phones. It is capable of delivering 1.3W of continuous average power into an 8Ω load with typically 1% distortion (THD+N) from a 5V battery voltage. It operates from 2.5V to 5.5V power supply.

The SGM4895 features a low power consumption shutdown mode. To facilitate this, shutdown may be enabled by logic low. Additionally, the SGM4895 features an internal thermal shutdown protection mechanism.

The SGM4895 contains advanced pop/click circuitry, with a minimal amount of external components. All these features make SGM4895 ideal for wireless handsets and other low voltage applications where minimal power consumption is a primary requirement.

The SGM4895 is available in Green TDFN-3×3-8L and MSOP-8 (Exposed Pad) packages. It operates over an ambient temperature range of -40°C to +85°C.

### FEATURES

- Fully Differential Amplifier
- Excellent PSRR: Direct Connection to Battery
- 1.3W into 8Ω Load from 5V Supply at THD+N = 1% (TYP)
- 1.6W into 4Ω Load from 5V Supply at THD+N = 1% (TYP, SGM4895YDB8 Only)
- 2.5V to 5.5V Operation
- Low Shutdown Current
- Improved Pop/Click Circuitry
- Support Single-Ended or Differential Input
- Thermal Overload Protection Circuitry
- No Output Coupling Capacitors, Bootstrap Capacitors Required
- External Gain Configuration Capability
- -40°C to +85°C Operating Temperature Range
- Green TDFN-3×3-8L and MSOP-8 (Exposed Pad) Packages

### APPLICATIONS

Portable Systems  
Wireless Handsets  
Mobile Phone  
Handheld Computers  
PDAs  
GPS

**PACKAGE/ORDERING INFORMATION**

MODEL	ORDER NUMBER	PACKAGE DESCRIPTION	PACKAGE OPTION	MARKING INFORMATION
SGM4895	SGM4895YDB8/TR	TDFN-3x3-8L	Tape and Reel, 3000	SGM4895DB
	SGM4895YPMS8/TR	MSOP-8 (Exposed Pad)	Tape and Reel, 3000	SGM4895YPMS8

**ABSOLUTE MAXIMUM RATINGS**

Supply Voltage.....	6V
Input Voltage.....	-0.3V to (V <sub>+</sub> ) + 0.3V
Storage Temperature Range .....	-65°C to +150°C
Junction Temperature.....	150°C
Operating Temperature Range.....	-40°C to +85°C
Lead Temperature Range (Soldering 10 sec) .....	260°C
ESD Susceptibility	
HBM.....	2000V
MM.....	400V

**NOTE:**

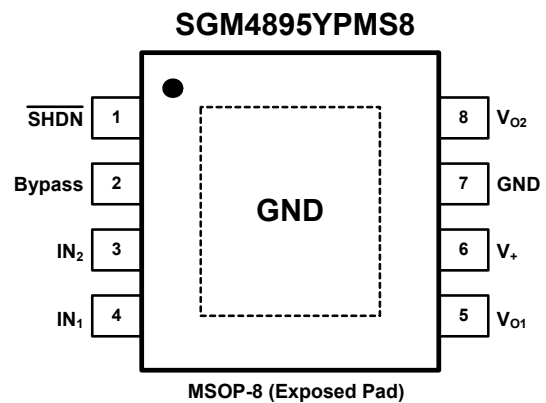
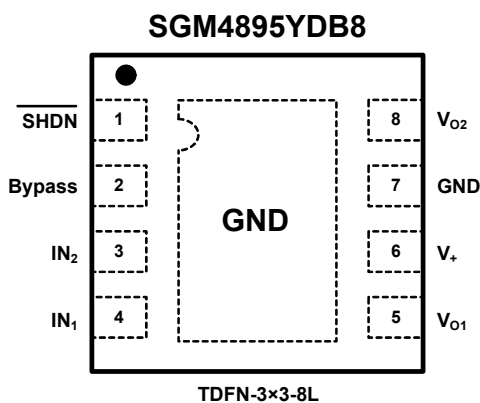
Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**CAUTION**

This integrated circuit can be damaged by ESD if you don't pay attention to ESD protection. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

SGMICRO reserves the right to make any change in circuit design, specification or other related things if necessary without notice at any time. Please contact SGMICRO sales office to get the latest datasheet.

**PIN CONFIGURATIONS (TOP VIEW)**



**ELECTRICAL CHARACTERISTICS**

(The following AC specifications apply for 8Ω load,  $A_V = 1V/V$ ,  $T_A = +25^\circ C$ , unless otherwise specified.)

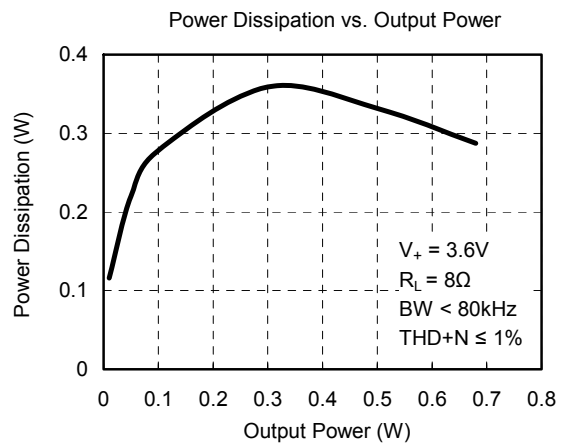
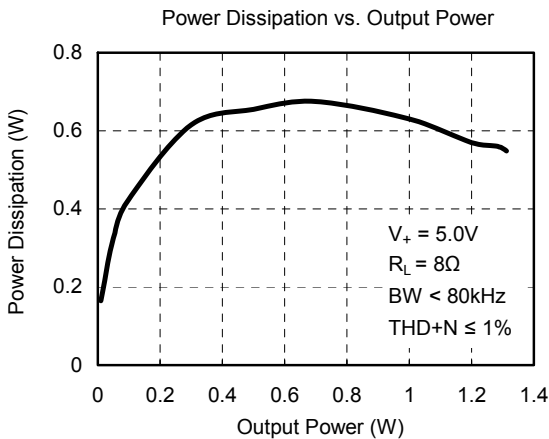
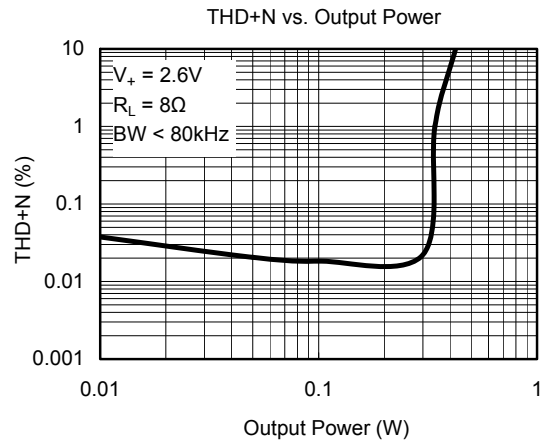
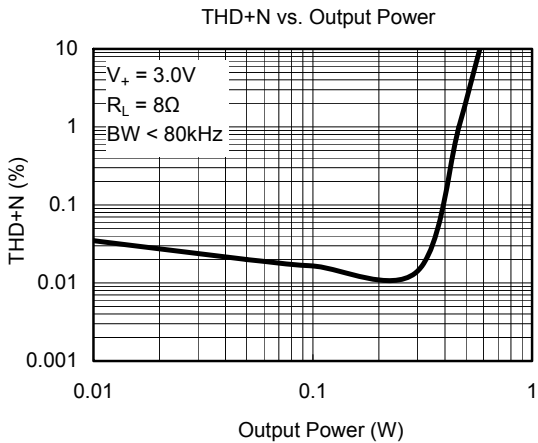
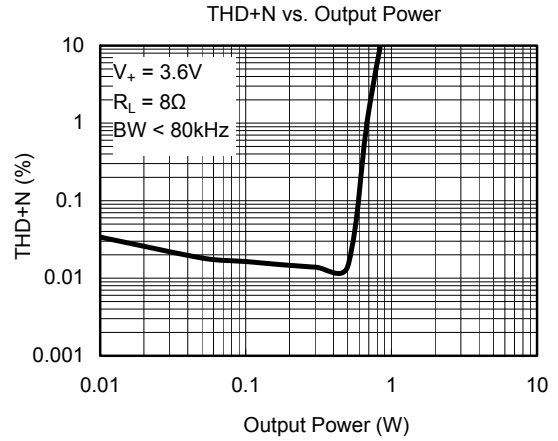
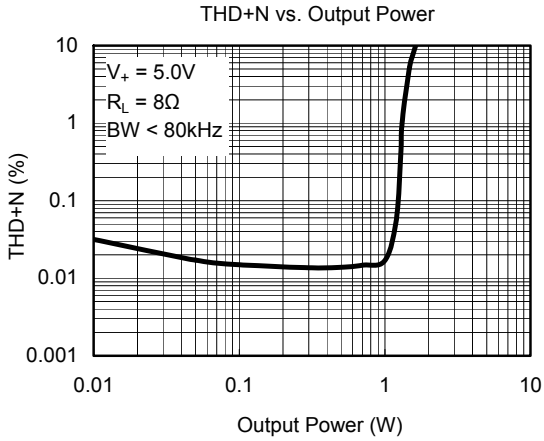
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	
Supply Voltage	$V_+$		2.5		5.5	V	
Shutdown Current	$I_{SD}$	$V_{IN} = 0V, V_{SHDN} = GND$		0.01	1	$\mu A$	
Output Offset Voltage	$V_{OS}$	$V_{IN} = 0V, V_{SHDN} = V_+ = 5.0V$	-10	2.5	10	mV	
		$V_{IN} = 0V, V_{SHDN} = V_+ = 3.3V$	-10	2.0	10		
		$V_{IN} = 0V, V_{SHDN} = V_+ = 2.6V$		2.0			
Quiescent Power Supply Current	$I_Q$	$V_{IN} = 0V, I_O = 0A, V_{SHDN} = V_+$	$V_+ = 5.0V, \text{No Load}$		4.70	7.50	mA
			$V_+ = 5.0V, 8\Omega \text{ Load}$		4.75	8.00	
			$V_+ = 3.3V, \text{No Load}$		3.87	5.80	
			$V_+ = 3.3V, 8\Omega \text{ Load}$		3.90	6.00	
			$V_+ = 2.6V, \text{No Load}$		3.20		
			$V_+ = 2.6V, 8\Omega \text{ Load}$		3.22		
Shutdown Voltage Input High	$V_{SDIH}$		1.2			V	
Shutdown Voltage Input Low	$V_{SDIL}$				0.4	V	
Output Power (8Ω)	$P_O$	$f = 1\text{kHz}$ THD+N = 1%	$V_+ = 5.0V$		1.30		W
			$V_+ = 3.6V$		0.65		
			$V_+ = 3.0V$		0.45		
			$V_+ = 2.6V$		0.34		
		$f = 1\text{kHz}$ THD+N = 10%	$V_+ = 5.0V$		1.60		
			$V_+ = 3.6V$		0.82		
			$V_+ = 3.0V$		0.55		
			$V_+ = 2.6V$		0.42		
Output Power (4Ω)	$P_O$	$f = 1\text{kHz}$ THD+N = 1% SGM4895YDB8 only	$V_+ = 5.0V$		1.60		W
			$V_+ = 3.6V$		1.00		
			$V_+ = 3.0V$		0.65		
			$V_+ = 2.6V$		0.50		
		$f = 1\text{kHz}$ THD+N = 10% SGM4895YDB8 only	$V_+ = 5.0V$		2.20		
			$V_+ = 3.6V$		1.25		
			$V_+ = 3.0V$		0.85		
			$V_+ = 2.6V$		0.60		
Total Harmonic Distortion + Noise	THD+N	$P_O = 0.6W_{rms}, f = 1\text{kHz}, V_+ = 5.0V$		0.015		%	
Power Supply Rejection Ratio <sup>(1)(2)</sup>	PSRR	$f = 217\text{Hz}$	$V_+ = 5.0V$		-83		dB
			$V_+ = 3.6V$		-80		
			$V_+ = 3.0V$		-73		
			$V_+ = 2.6V$		-65		
		$f = 1\text{kHz}$	$V_+ = 5.0V$		-83		
			$V_+ = 3.6V$		-80		
			$V_+ = 3.0V$		-73		
			$V_+ = 2.6V$		-65		
Common Mode Rejection Ratio <sup>(2)</sup>	CMRR	$f = 217\text{Hz}, V_{CM} = 200mV_{P-P}, V_+ = 5.0V$		-76		dB	
Wake-Up Time	$T_{WU}$	$C_B = 1\mu F$	$V_+ = 5.0V$		50		ms
			$V_+ = 3.6V$		42		
			$V_+ = 3.0V$		37		
			$V_+ = 2.6V$		32		

NOTES:

- 10Ω terminated input.
- PSRR and CMRR are affected by the matching between gain-setting resistor ratios.

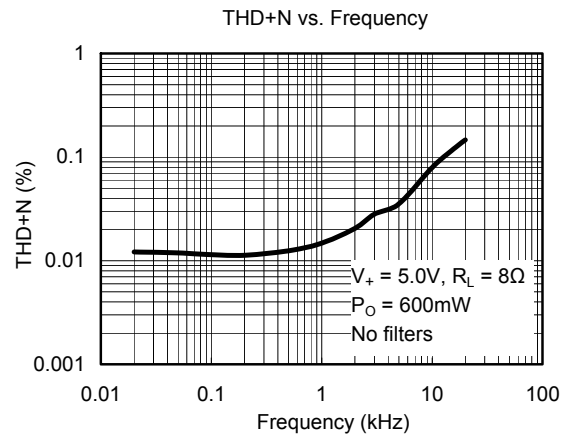
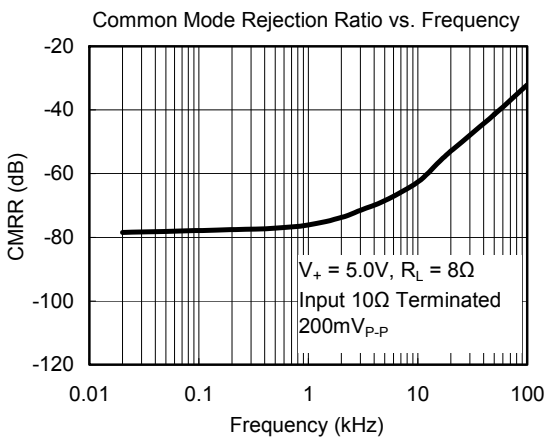
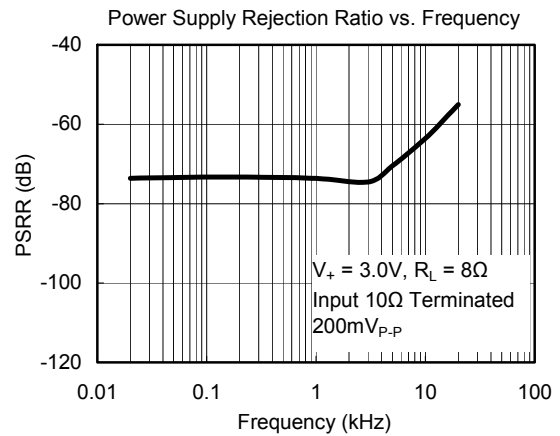
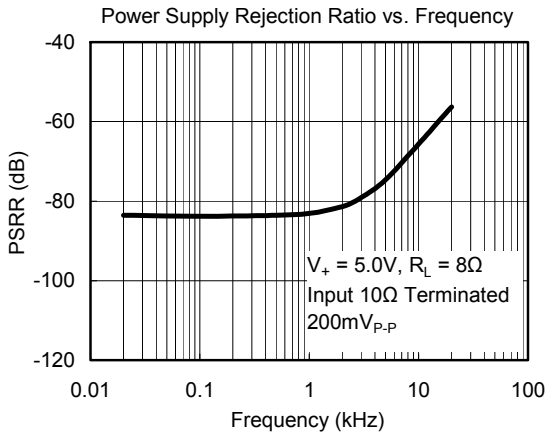
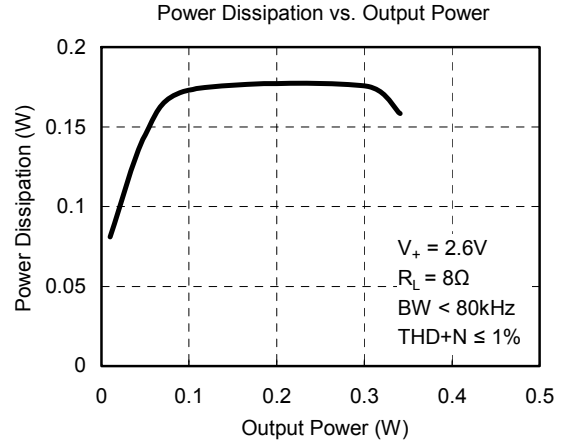
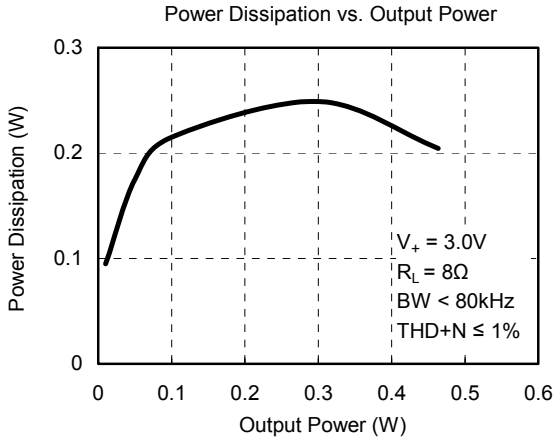
TYPICAL PERFORMANCE CHARACTERISTICS

At  $T_A = +25^\circ\text{C}$ ,  $A_V = 1$ ,  $f = 1\text{kHz}$ ,  $C_B = 1\mu\text{F}$ , unless otherwise noted.



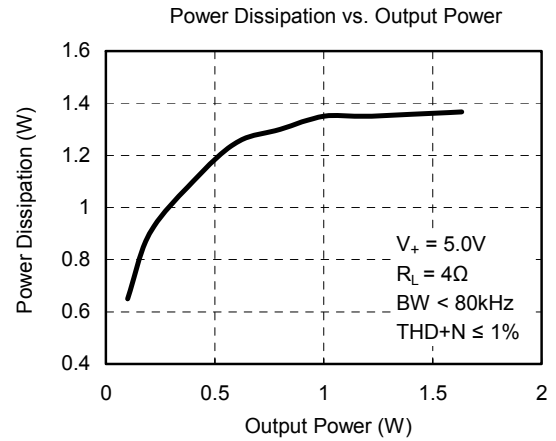
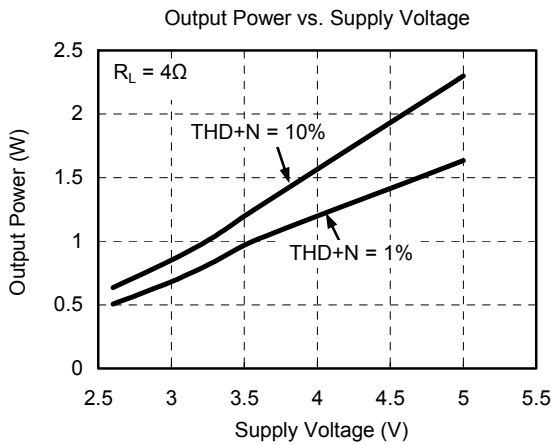
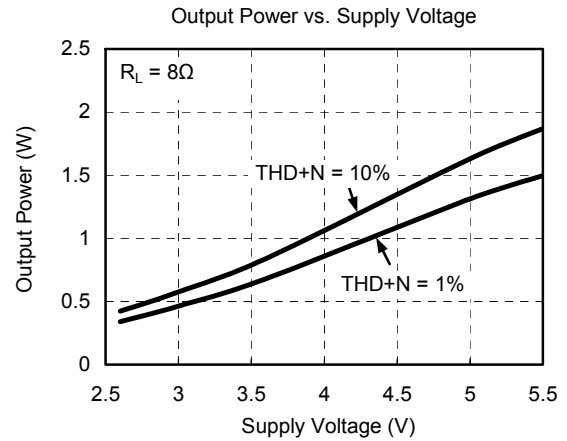
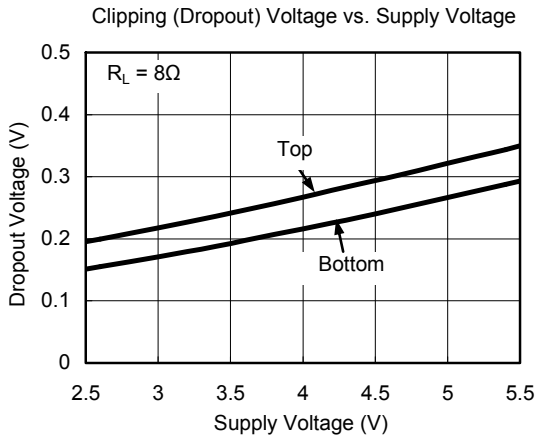
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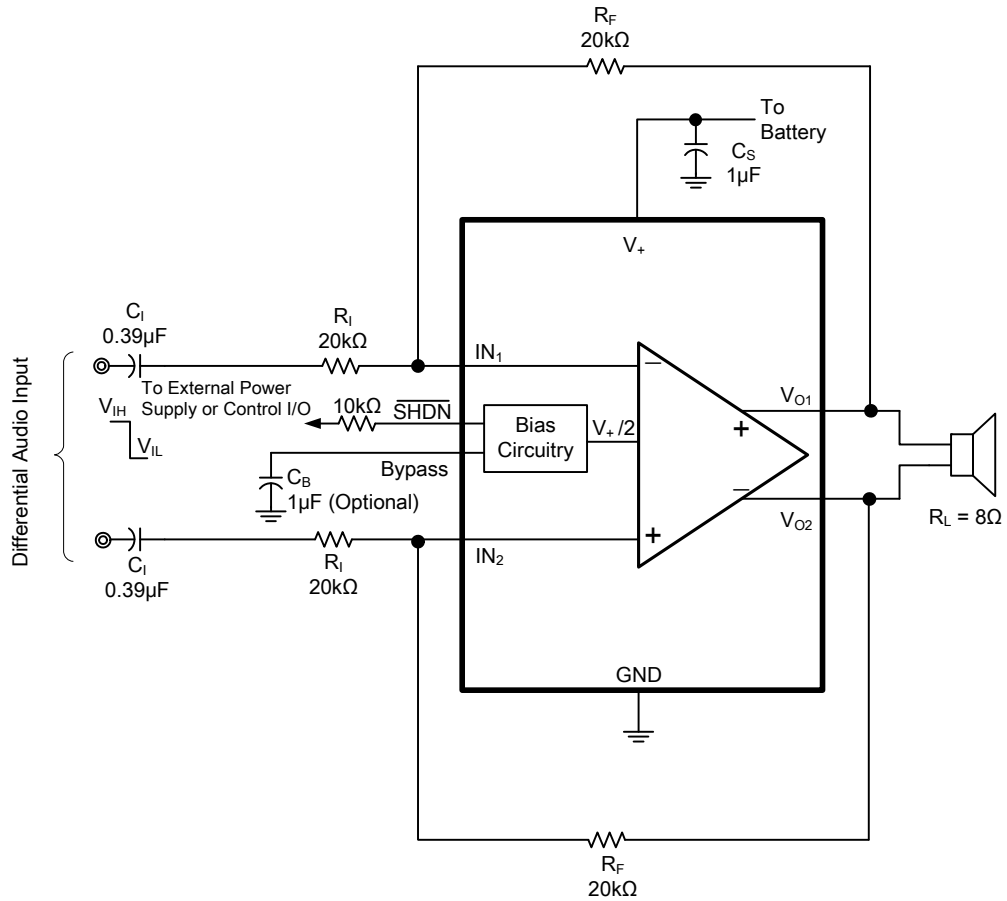


**TYPICAL PERFORMANCE CHARACTERISTICS**

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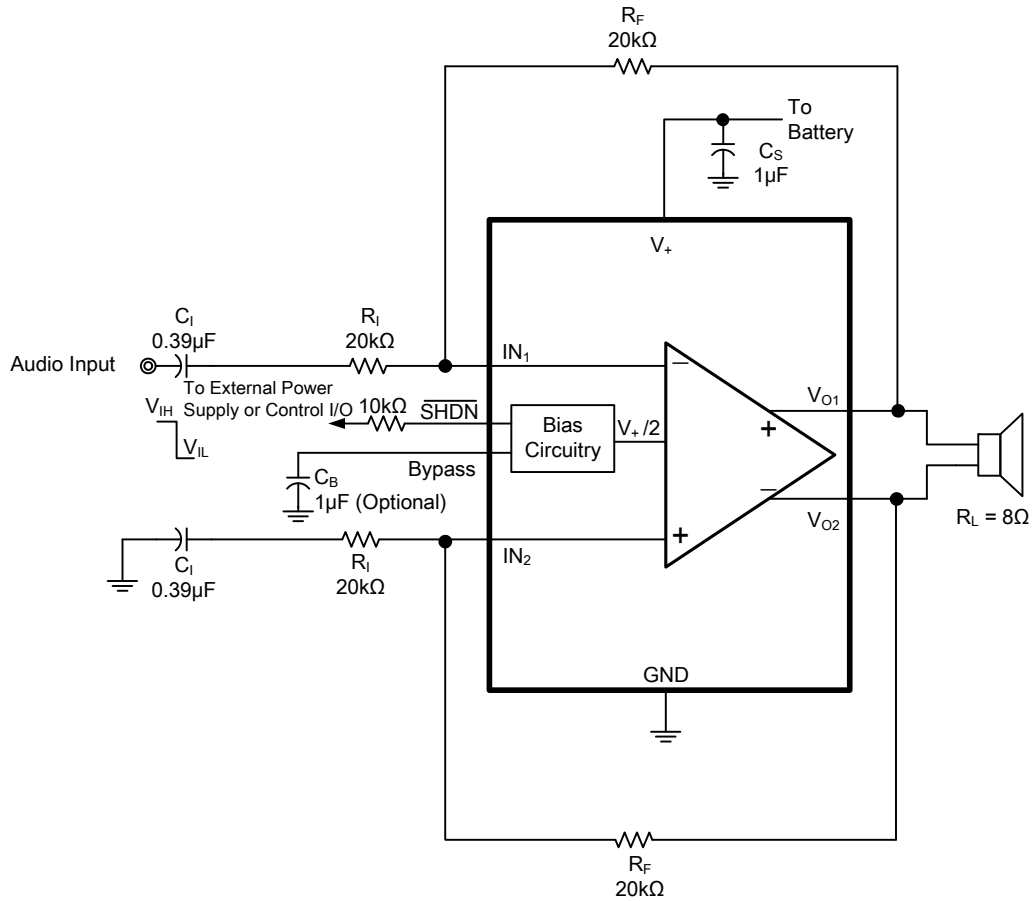
TYPICAL APPLICATIONS



NOTE: A 10kΩ resistor must be serially connected to  $\overline{\text{SHDN}}$  pin.

Figure 1. Typical Differential Input Application Schematic

TYPICAL APPLICATIONS



NOTE: A 10kΩ resistor must be serially connected to  $\overline{\text{SHDN}}$  pin.

Figure 2. Single-Ended Input Application Schematic



## APPLICATION NOTES

### PCB Design Recommendations (Thermal Design Considerations)

With proper thermal design considerations, SGM4895YDB8 is capable of delivering 1.6W of continuous average power into a 4Ω load at 5V power supply.

#### Thermal Land

The TDFN-3×3-8L thermal land is a metal (normally copper) region centrally located under the package and on top of the PCB. It has a rectangular or square shape and should match the dimensions of the exposed pad on the bottom of the package (1:1 ratio).

For certain high power applications, the PCB land may be modified to a "dog bone" shape that enhances thermal performance. The packages used with the "dog bone" lands will be a dual inline configuration (see Figure 3).

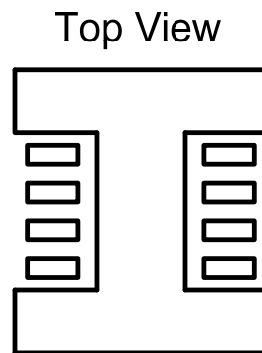


Figure 3. Dog Bone

#### Thermal Vias

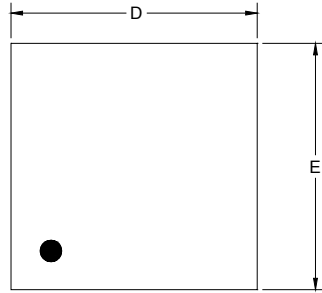
Thermal vias are necessary. They conduct heat from the exposed pad of the package to the ground plane. The number of vias is application specific and is dependent upon electrical requirements and power dissipation.

The via diameter should be 0.2mm to 0.33mm with 1oz. copper via barrel plating. It is important to plug the via to avoid any solder wicking inside the via during the soldering process. The thermal vias can be tented with solder mask on the top surface of the PCB. The solder mask diameter should be at least 75microns (or 3mils) larger than the via diameter. The solder mask thickness should be the same across the entire PCB.

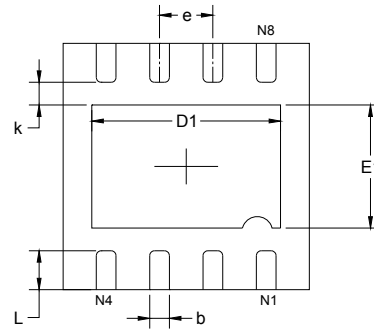
A package thermal performance may be improved by increasing the number of vias.

PACKAGE OUTLINE DIMENSIONS

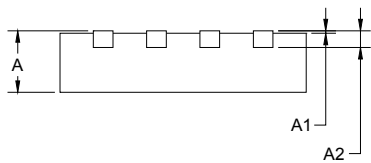
TDFN-3x3-8L



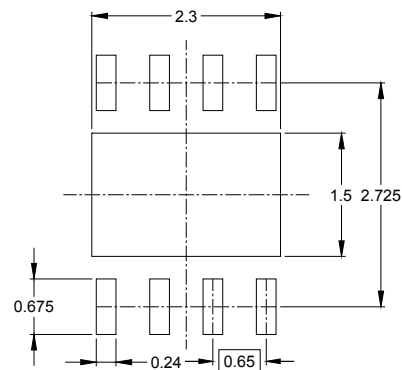
TOP VIEW



BOTTOM VIEW



SIDE VIEW

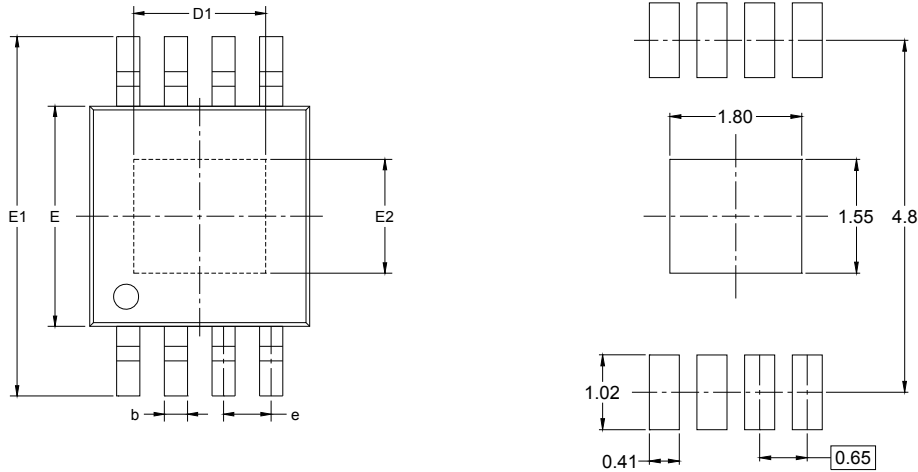


RECOMMENDED LAND PATTERN (Unit: mm)

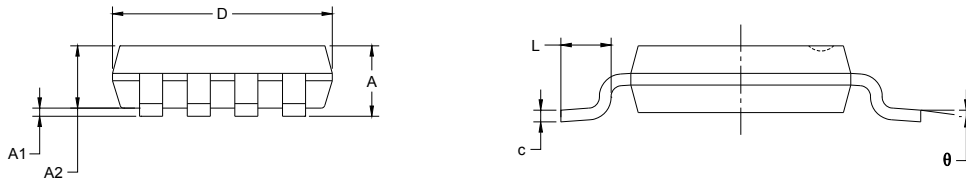
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A2	0.203 REF		0.008 REF	
D	2.900	3.100	0.114	0.122
D1	2.200	2.400	0.087	0.094
E	2.900	3.100	0.114	0.122
E1	1.400	1.600	0.055	0.063
k	0.200 MIN		0.008 MIN	
b	0.180	0.300	0.007	0.012
e	0.650 TYP		0.026 TYP	
L	0.375	0.575	0.015	0.023

PACKAGE OUTLINE DIMENSIONS

MSOP-8 (Exposed Pad)



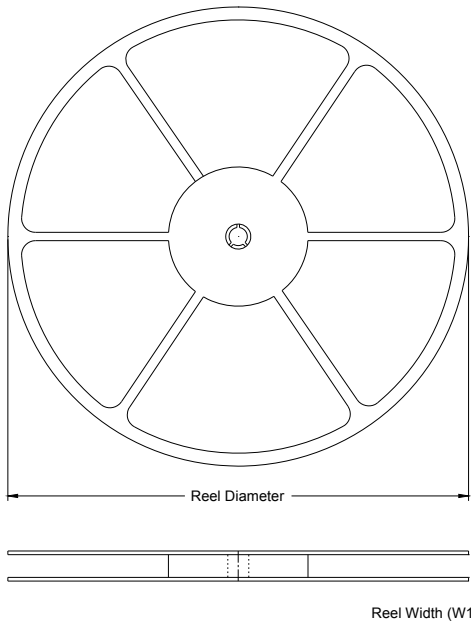
RECOMMENDED LAND PATTERN (Unit: mm)



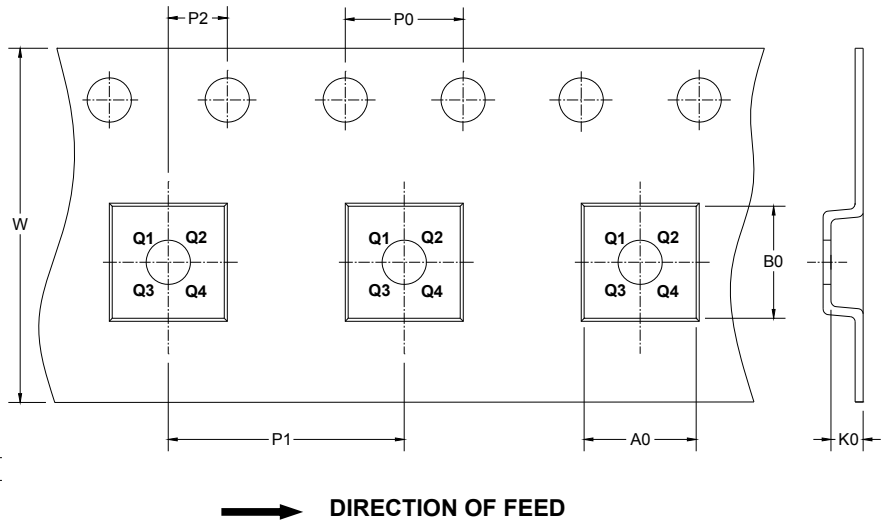
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	0.820	1.100	0.032	0.043
A1	0.020	0.150	0.001	0.006
A2	0.750	0.950	0.030	0.037
b	0.250	0.380	0.010	0.015
c	0.090	0.230	0.004	0.009
D	2.900	3.100	0.114	0.122
D1	1.700	1.900	0.067	0.075
e	0.65 BSC		0.026 BSC	
E	2.900	3.100	0.114	0.122
E1	4.750	5.050	0.187	0.199
E2	1.450	1.650	0.057	0.065
L	0.400	0.800	0.016	0.031
θ	0°	6°	0°	6°

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

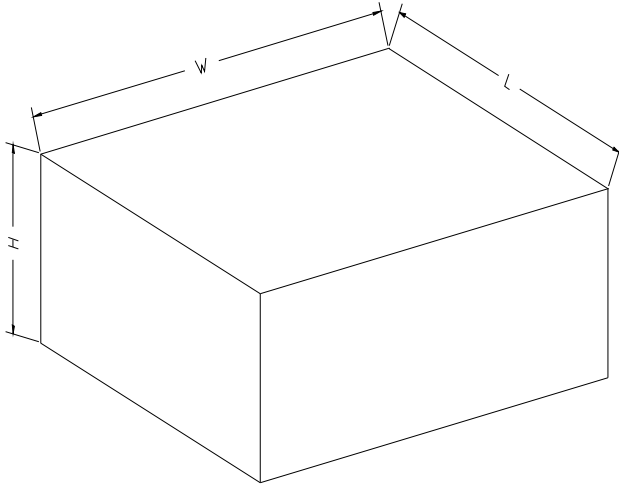
KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
MSOP-8 (Exposed Pad)	13"	12.4	5.2	3.3	1.5	4.0	8.0	2.0	12.0	Q1
TDFN-3x3-8L	13"	12.4	3.35	3.35	1.13	4.00	8.00	2.00	12.00	Q1

# SGM4895

# 1.3W Fully Differential Audio Power Amplifier

## CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

## KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
13"	386	280	370	5